



Printed Circuit Boards
Interconnection Carriers

State of the Art: PCB's

Revisio

Datum:

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PRINTED CIRCUIT BOARDS

01

4.11.2001

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Schematic Key for Multilayer and HDI-Technology Build-Ups

| a | b | c | d | e | f | g + h + i |
|---|---|---|---|---|---|-----------|
|---|---|---|---|---|---|-----------|

04 310 FR4 100 L90.100 P18

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

04_310_FR4_100_L90.100_p18

| Layers | in μ | Material | Build-Up | Assembly | | |
|----------|-----------|----------|----------|----------|--------------------------------|--|
| Layer-1 | 100 μ | Copper | | | | |
| | 180 μ | Prepreg | | | (180 μ PrePreg-Type: 7628) | |
| | 180 μ | Prepreg | | | | |
| | 180 μ | Prepreg | | | | |
| | 180 μ | Prepreg | | | | |
| | 180 μ | Prepreg | | | | |
| Layer-2 | 100 μ | Copper | | | | |
| | 900 μ | L-FR4 | | | | |
| Layer-3 | 100 μ | Copper | | | | |
| | 180 μ | Prepreg | | | | |
| | 180 μ | Prepreg | | | | |
| | 180 μ | Prepreg | | | | |
| | 180 μ | Prepreg | | | | |
| | 180 μ | Prepreg | | | | |
| Layer-99 | 100 μ | Copper | | | | |

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